

IN THE CLAIMS

Claims 1-20 (Canceled).

21 (Original). A device comprising:

- a first semiconductor structure having front and back sides;
- a microelectromechanical system formed on said front side of said first structure;
- a second structure bonded to said first structure by a surface mount connection, said connection including a solder bump that defines a hermetic cavity between said first and second structures surrounding said system;
- an open area in said first structure under said system; and
- a film applied to the back side of said first semiconductor structure forming said open area between said first semiconductor structure and said film.

22 (Original). The device of claim 21 wherein said film is a plastic film.

23 (Original). The device of claim 22 wherein said film is adhesively secured to said back side.

24 (Original). The device of claim 21 wherein said first and second structures are semiconductor structures.

25 (Original). The device of claim 21 wherein said second structure is an insulator.

26 (Original). The device of claim 25 wherein said second structure is glass.

27 (Original). The device of claim 26 including an aperture through said second structure said aperture being filled by a solder bump that extends completely through said second structure.

28 (Original). The device of claim 21 wherein said system is a film bulk acoustic resonator.

29 (Original). The device of claim 21 wherein said system is a switch.

30 (Original). The system of claim 21 wherein said system is a transmission line.